



STF130N10F3, STFI130N10F3, STH130N10F3-2, STP130N10F3

N-channel 100 V, 7.8 mΩ typ., 120 A STripFET™III Power MOSFET
in TO-220FP, I²PAKFP, H²PAK-2 and TO-220 packages

Datasheet — production data

Features

Order codes	V _{DSS}	R _{DS(on)} max.	I _D
STF130N10F3	100 V	9.6 mΩ	46 A
STFI130N10F3			
STH130N10F3-2		9.3 mΩ	120 A
STP130N10F3		9.6 mΩ	

- Ultra low on-resistance
- 100% avalanche tested

Applications

- High current switching applications

Description

These devices are N-channel enhancement mode Power MOSFETs produced using STMicroelectronics' STripFET™ III technology, which is specifically designed to minimize on-resistance and gate charge to provide superior switching performance.

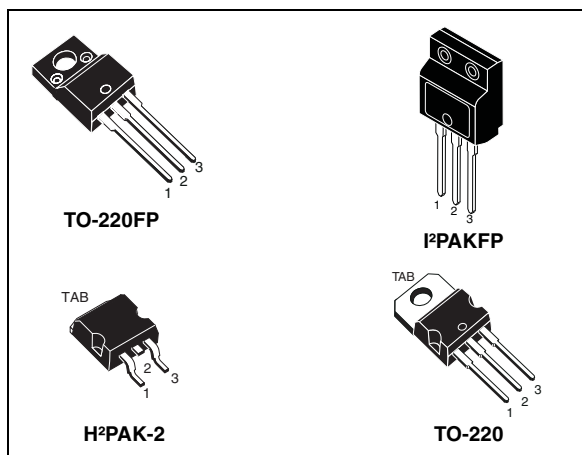


Figure 1. Internal schematic diagram

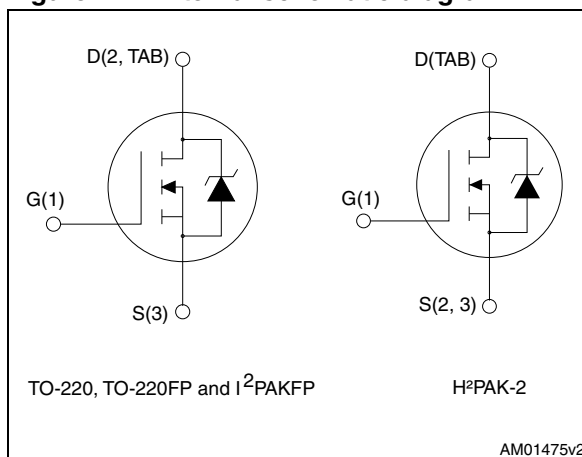


Table 1. Device summary

Order codes	Marking	Package	Packaging
STF130N10F3	130N10F3	TO-220FP	Tube
STFI130N10F3		I ² PAKFP	Tube
STH130N10F3-2		H ² PAK-2	Tape and reel
STP130N10F3		TO-220	Tube

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1 Electrical ratings

Table 2. Absolute maximum ratings

Symbol	Parameter	Value			Unit
		TO-220FP I ² PAKFP	H ² PAK-2	TO-220	
V_{DS}	Drain-source voltage	100			V
V_{GS}	Gate-source voltage	± 20			V
$I_D^{(1)}$	Drain current (continuous) at $T_C = 25^\circ\text{C}$	46	120		A
$I_D^{(1)}$	Drain current (continuous) at $T_C = 100^\circ\text{C}$	29	78		A
$I_{DM}^{(2)}$	Drain current (pulsed)	184	450		A
P_{TOT}	Total dissipation at $T_C = 25^\circ\text{C}$	35	250		W
dv/dt	Peak diode recovery voltage slope	22			V/ns
V_{ISO}	Insulation withstand voltage (RMS) from all three leads to external heat sink ($t = 1$ s; $T_C = 25^\circ\text{C}$)	2500			V
$E_{AS}^{(3)}$	Single pulse avalanche energy	125			mJ
T_j T_{stg}	Operating junction temperature storage temperature	- 55 to 175			$^\circ\text{C}$

1. Current limited by package.
2. Pulse width limited by safe operating area.
3. Starting $T_j = 25^\circ\text{C}$, $I_D = 50$ A, $V_{DD} = 50$ V for TO-220 and H²PAK-2; Starting $T_j = 25^\circ\text{C}$, $I_D = 29$ A, $V_{DD} = 60$ V for I²PAKFP and TO-220FP.

Table 3. Thermal data

Symbol	Parameter	Value			Unit
		TO-220FP I ² PAKFP	H ² PAK-2	TO-220	
Rthj-case	Thermal resistance junction-case	4.3	0.6	0.6	$^\circ\text{C/W}$
Rthj-a	Thermal resistance junction-ambient	62.5		62.5	$^\circ\text{C/W}$
Rthj-pcb ⁽¹⁾	Thermal resistance junction-pcb		35		$^\circ\text{C/W}$

1. When mounted on FR-4 board, on 1inch², 2oz Cu.

2 Electrical characteristics

($T_{CASE} = 25\text{ }^{\circ}\text{C}$ unless otherwise specified)

Table 4. On/off states

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-source breakdown voltage	$V_{GS} = 0, I_D = 250\text{ }\mu\text{A}$	100	-		V
I_{DSS}	Zero gate voltage drain current	$V_{GS} = 0, V_{DS} = 100\text{ V}$ $T_C = 25^{\circ}\text{C}$ $T_C = 125^{\circ}\text{C}$		-	10 100	μA μA
I_{GSS}	Gate body leakage current	$V_{DS} = 0, V_{GS} = \pm 20\text{ V}$		-	± 200	nA
$V_{GS(th)}$	Gate threshold voltage	$V_{DS} = V_{GS}, I_D = 250\text{ }\mu\text{A}$	2	-	4	V
$R_{DS(on)}$	Static drain-source on-resistance	$V_{GS} = 10\text{ V}, I_D = 23\text{ A}$ TO-220FP and I ² PAKFP		8	9.6	m Ω
		$V_{GS} = 10\text{ V}, I_D = 60\text{ A}$ H ² PAK TO-220		7.8 8	9.3 9.6	

Table 5. Dynamic

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
C_{iss}	Input capacitance	$V_{GS} = 0, V_{DS} = 25\text{ V},$ $f = 1\text{ MHz}$	-	3305	-	pF
C_{oss}	Output capacitance			373		pF
C_{rss}	Reverse transfer capacitance			23		pF
Q_g	Total gate charge	$V_{DD} = 50\text{ V}, I_D = 120\text{ A},$	-	57	-	nC
Q_{gs}	Gate-source charge	$V_{GS} = 10\text{ V}$		22		nC
Q_{gd}	Gate-drain charge	(see Figure 20)		17		nC

Table 6. Switching times

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on delay time	$V_{DD} = 50\text{ V}, I_D = 60\text{ A}$ $R_G = 4.7\text{ }\Omega, V_{GS} = 10\text{ V}$ (see Figure 19 , Figure 24)	-	17	-	ns
t_r	Rise time			38		ns
$t_{d(off)}$	Turn-off delay time			52		ns
t_f	Fall time			7.2		ns

Table 7. Source drain diode

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
I_{SD} $I_{SDM}^{(1)}$	Source-drain current Source-drain current (pulsed)	For TO-220FP and I ² PAKFP	-		46 184	A A
I_{SD} $I_{SDM}^{(2)}$	Source-drain current Source-drain current (pulsed)	For TO-220, H ² PAK-2	-		120 450	A A
$V_{SD}^{(3)}$	Forward on voltage	$I_{SD}=120\text{ A}$, $V_{GS}=0$; for TO-220, H ² PAK-2	-		1.5	V
		$I_{SD}=46\text{ A}$, $V_{GS}=0$; for TO-220FP and I ² PAKFP				
t_{rr} Q_{rr} I_{RRM}	Reverse recovery time Reverse recovery charge Reverse recovery current	$I_{SD}=120\text{ A}$, $di/dt = 100\text{ A}/\mu\text{s}$, $V_{DD}=80\text{ V}$, $T_j=150\text{ }^{\circ}\text{C}$ (see Figure 21)	-	68 182 5.4		ns nC A

1. Pulse width limited by safe operating area
2. Pulse width limited by safe operating area
3. Pulsed: pulse duration = 300 μs , duty cycle 1.5%

2.1 Electrical characteristics (curves)

Figure 2. Safe operating area for TO-220FP and I²PAKFP

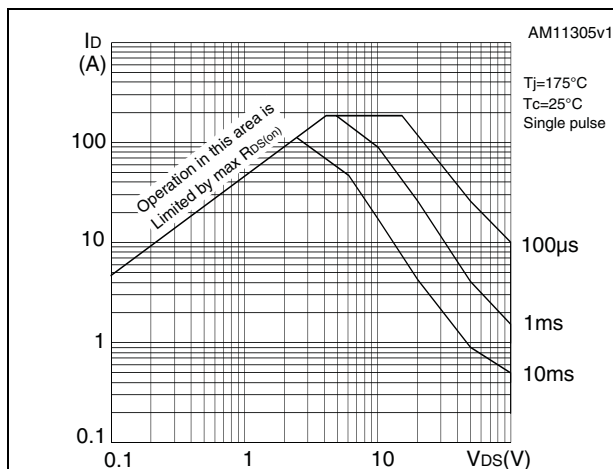


Figure 3. Thermal impedance for TO-220FP and I²PAKFP

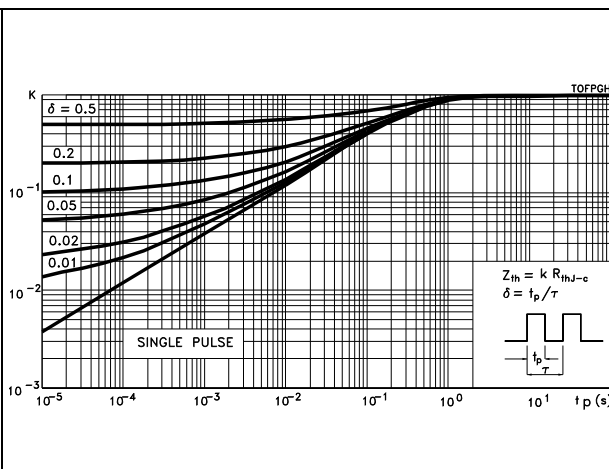


Figure 4. Safe operating area for H²PAK-2 and TO-220

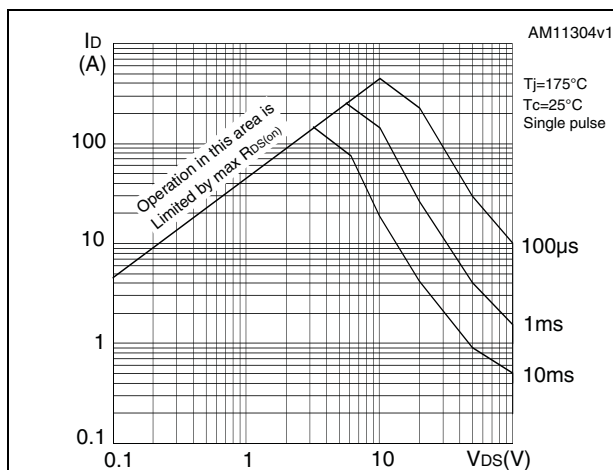


Figure 5. Thermal impedance for H²PAK-2 and TO-220

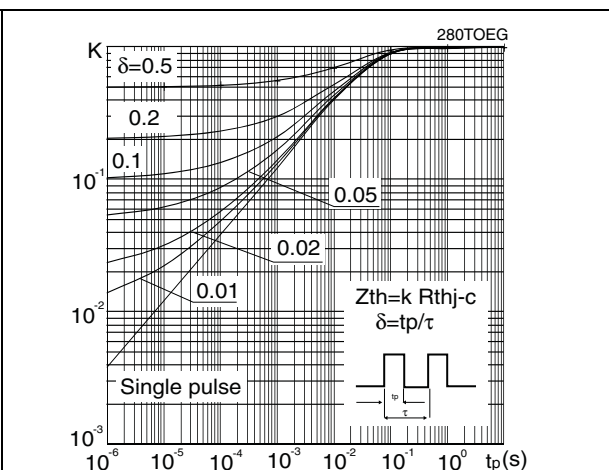


Figure 6. Output characteristics

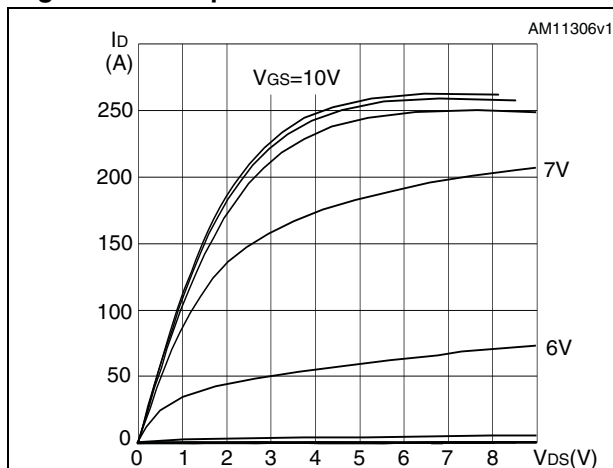


Figure 7. Transfer characteristics

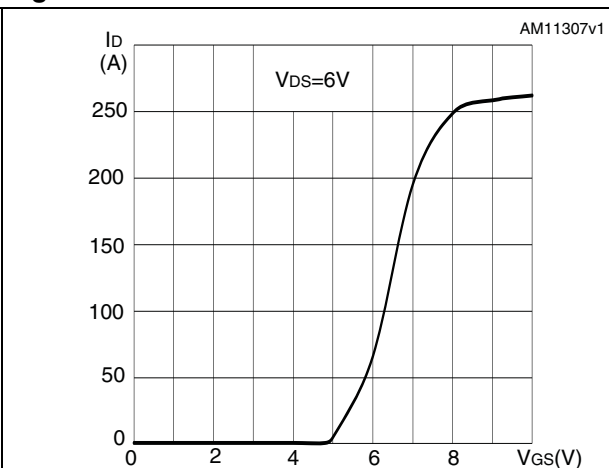


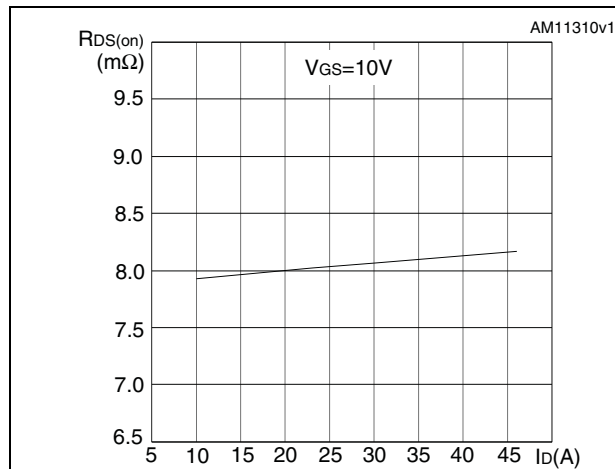
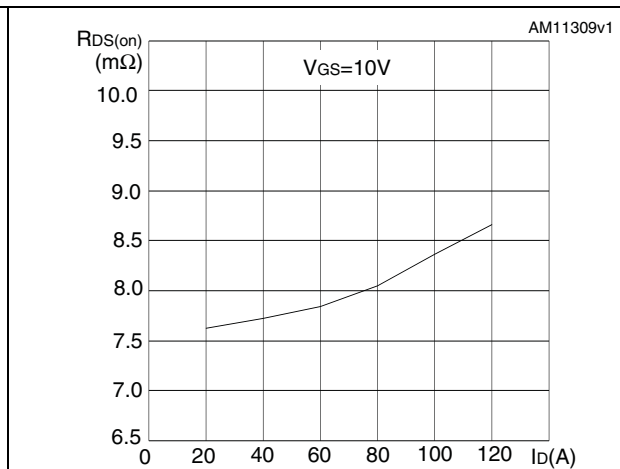
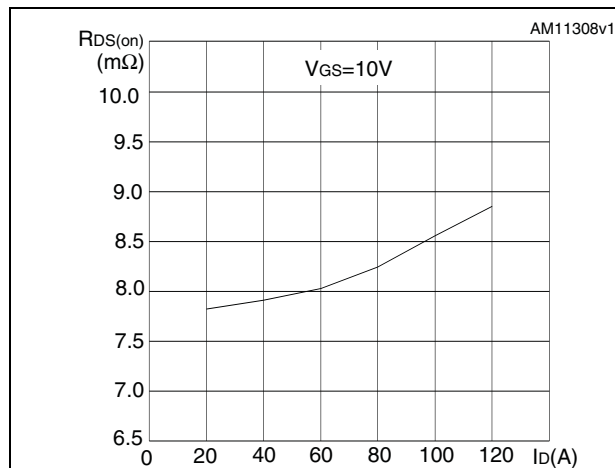
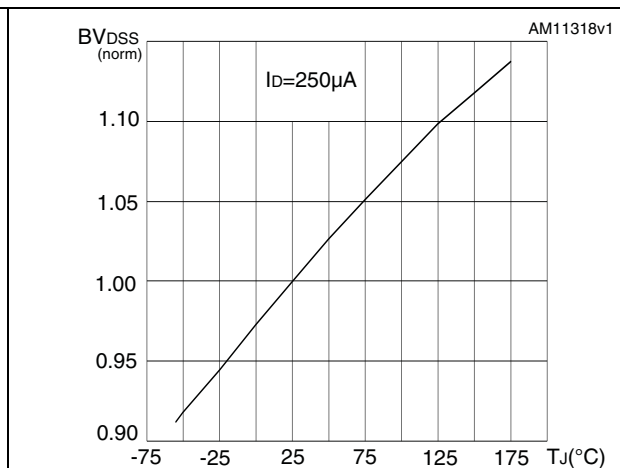
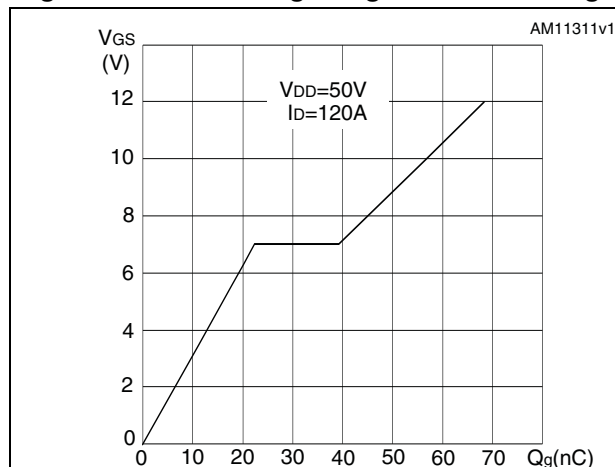
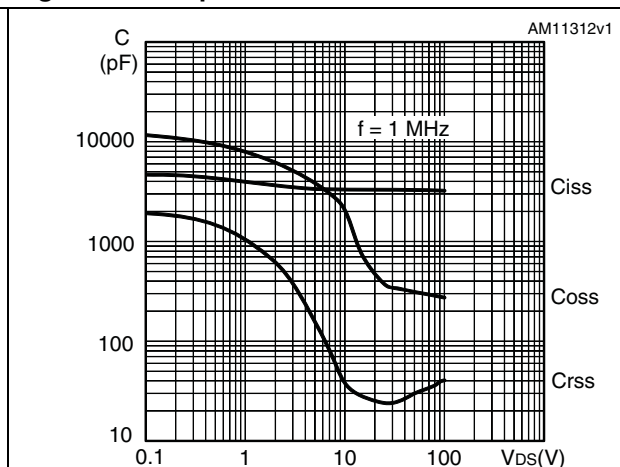
Figure 8. Static drain-source on-resistance for TO-220FP and I²PAKFP**Figure 9. Static drain-source on-resistance for H²PAK-2****Figure 10. Static drain-source on-resistance for TO-220****Figure 11. Normalized B_{VDSS} vs temperature****Figure 12. Gate charge vs gate-source voltage****Figure 13. Capacitance variations**

Figure 14. Normalized gate threshold voltage vs temperature

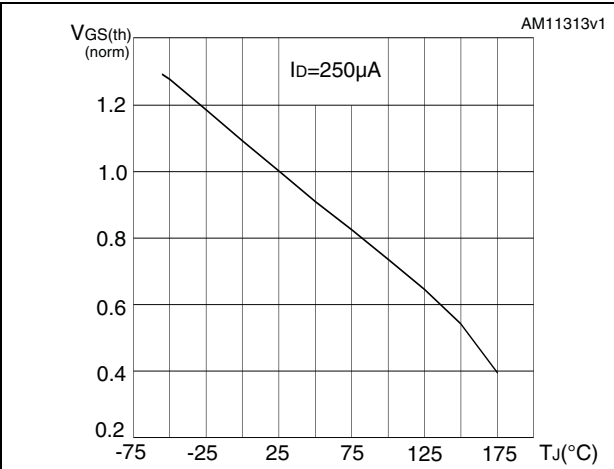


Figure 15. Normalized on-resistance vs temperature for TO-220FP and I²PAKFP

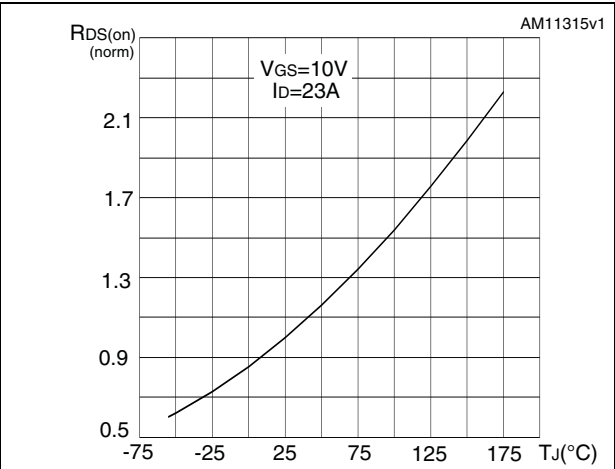


Figure 16. Normalized on resistance vs temperature for H²PAK-2 and TO-220

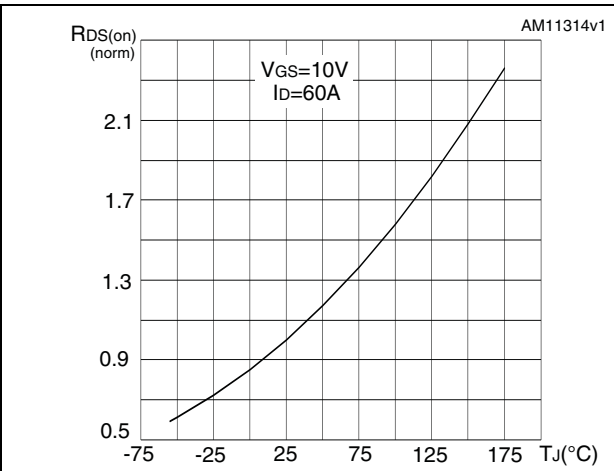


Figure 17. Source-drain diode forward characteristics for TO-220FP and I²PAKFP

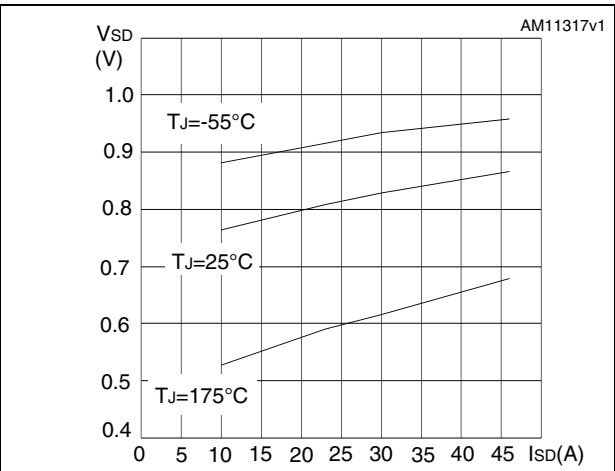
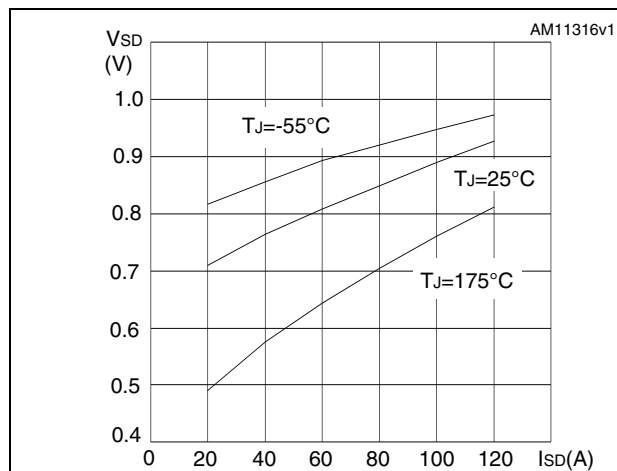


Figure 18. Source-drain diode forward characteristics for H²PAK-2 and TO-220



3 Test circuits

Figure 19. Switching times test circuit for resistive load

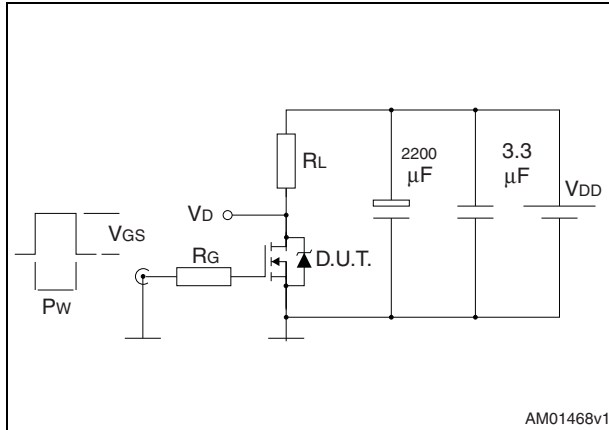


Figure 20. Gate charge test circuit

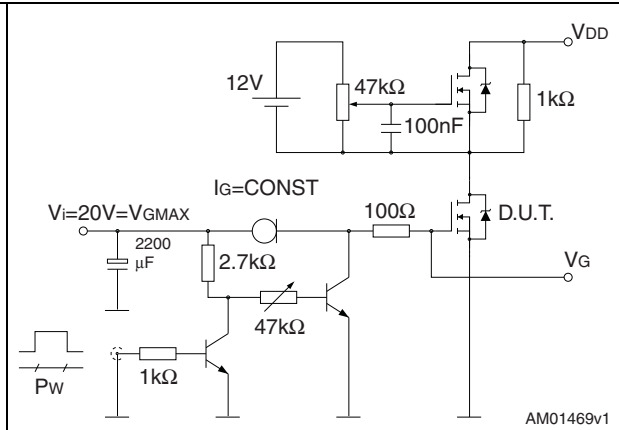


Figure 21. Test circuit for inductive load switching and diode recovery times

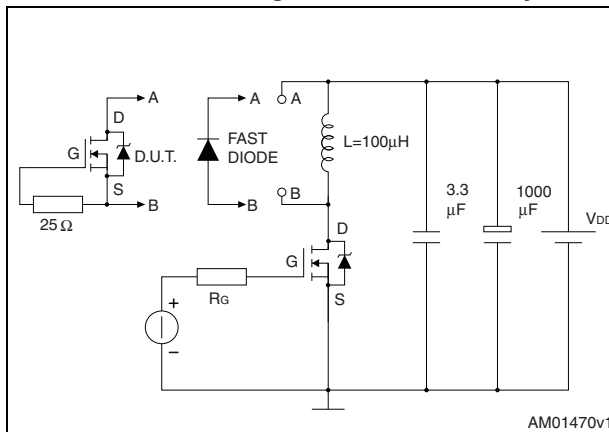


Figure 22. Unclamped inductive load test circuit

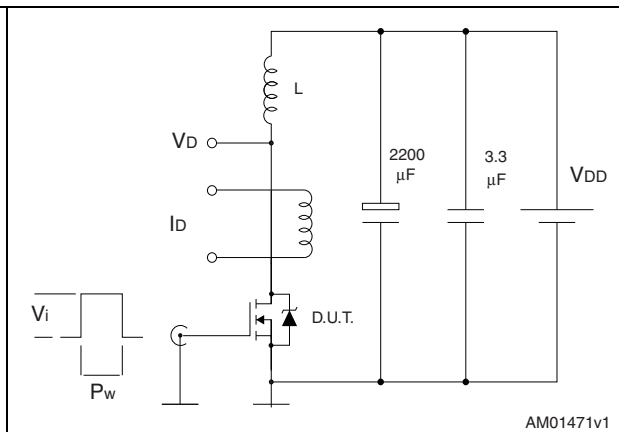


Figure 23. Unclamped inductive waveform

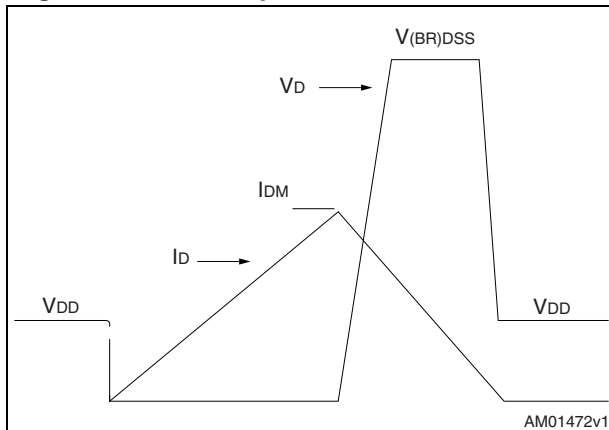
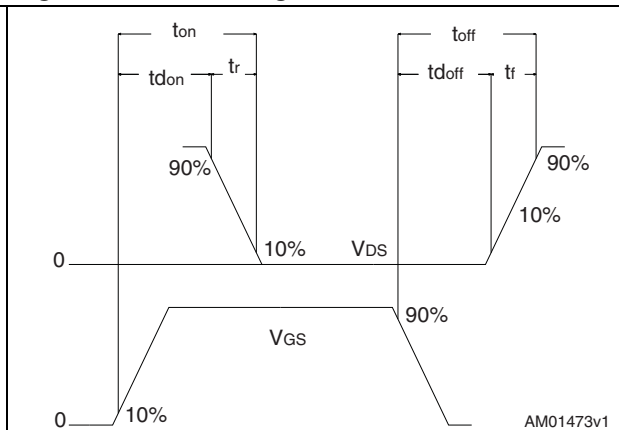


Figure 24. Switching time waveform



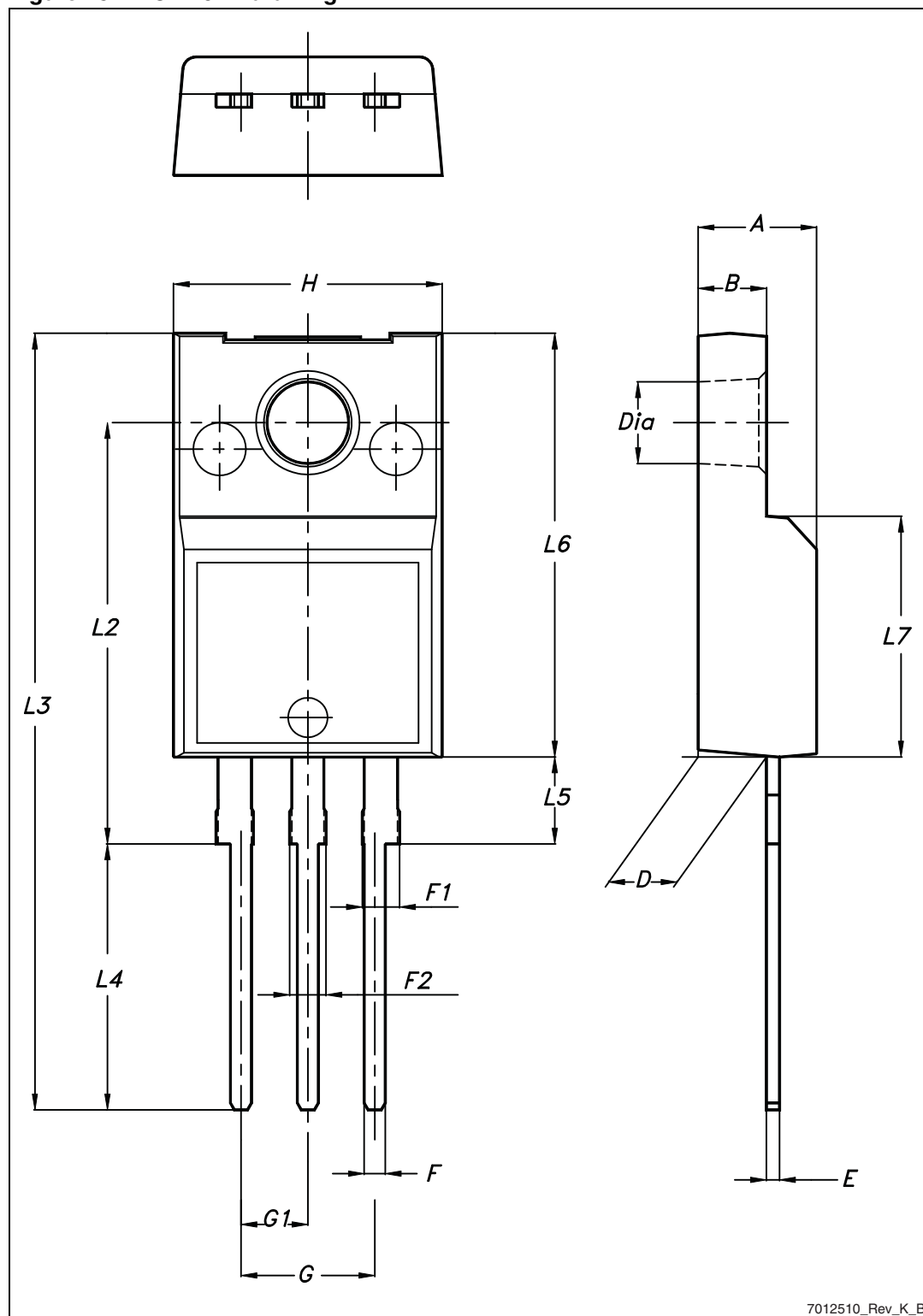
4 Package mechanical data

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com. ECOPACK is an ST trademark.

Table 8. TO-220FP mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	4.4		4.6
B	2.5		2.7
D	2.5		2.75
E	0.45		0.7
F	0.75		1
F1	1.15		1.70
F2	1.15		1.70
G	4.95		5.2
G1	2.4		2.7
H	10		10.4
L2		16	
L3	28.6		30.6
L4	9.8		10.6
L5	2.9		3.6
L6	15.9		16.4
L7	9		9.3
Dia	3		3.2

Figure 25. TO-220FP drawing



7012510_Rev_K_B

Table 9. I²PAKFP (TO-281) mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	4.40	-	4.60
B	2.50		2.70
D	2.50		2.75
D1	0.65		0.85
E	0.45		0.70
F	0.75		1.00
F1			1.20
G	4.95		5.20
H	10.00		10.40
L1	21.00		23.00
L2	13.20		14.10
L3	10.55		10.85
L4	2.70		3.20
L5	0.85		1.25
L6	7.30		7.50

Figure 26. I²PAKFP (TO-281) drawing

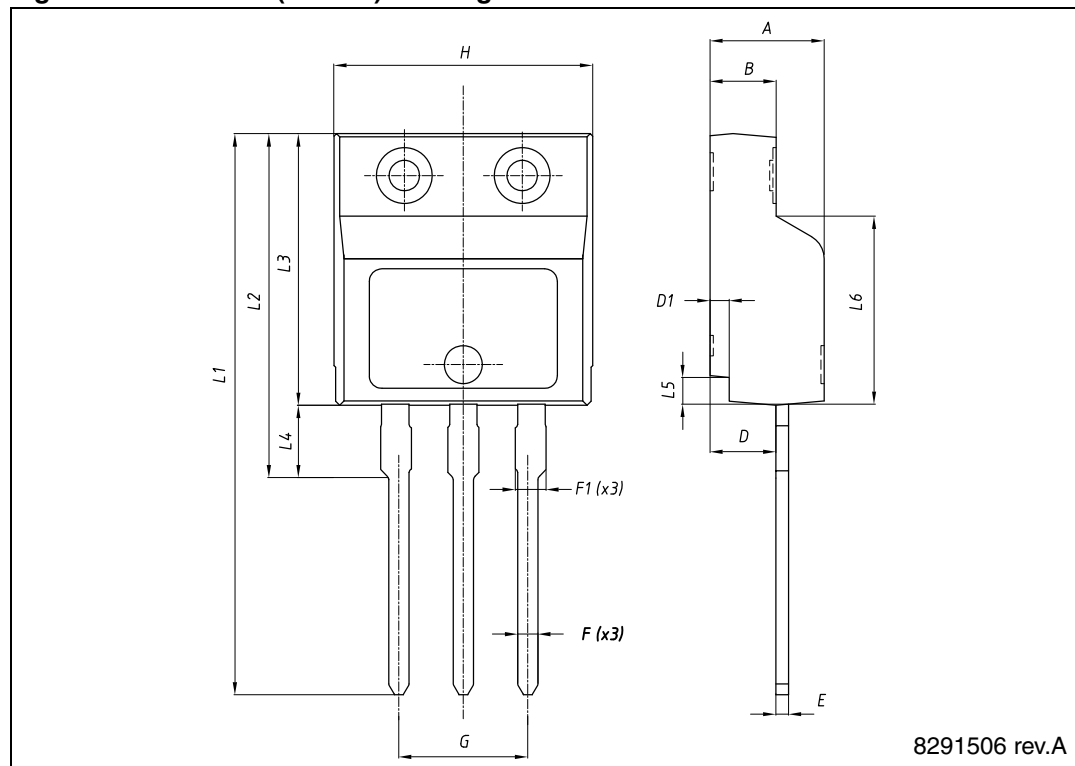


Table 10. H²PAK-2 mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	4.30	-	4.80
A1	0.03		0.20
C	1.17		1.37
e	4.98		5.18
E	0.50		0.90
F	0.78		0.85
H	10.00		10.40
H1	7.40		7.80
L	15.30		15.80
L1	1.27		1.40
L2	4.93		5.23
L3	6.85		7.25
L4	1.5		1.7
M	2.6		2.9
R	0.20		0.60
V	0°		8°

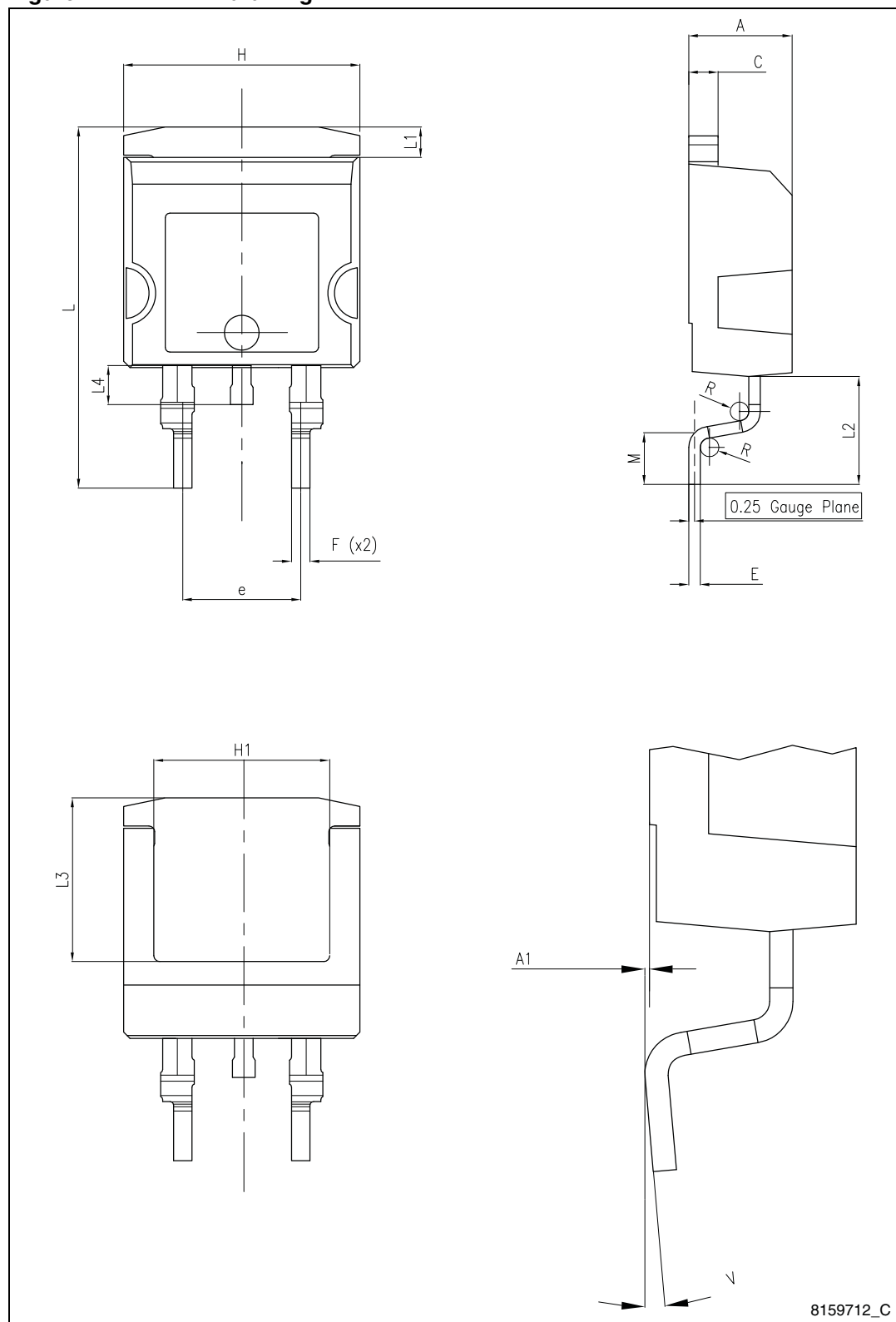
Figure 27. H²PAK-2 drawing

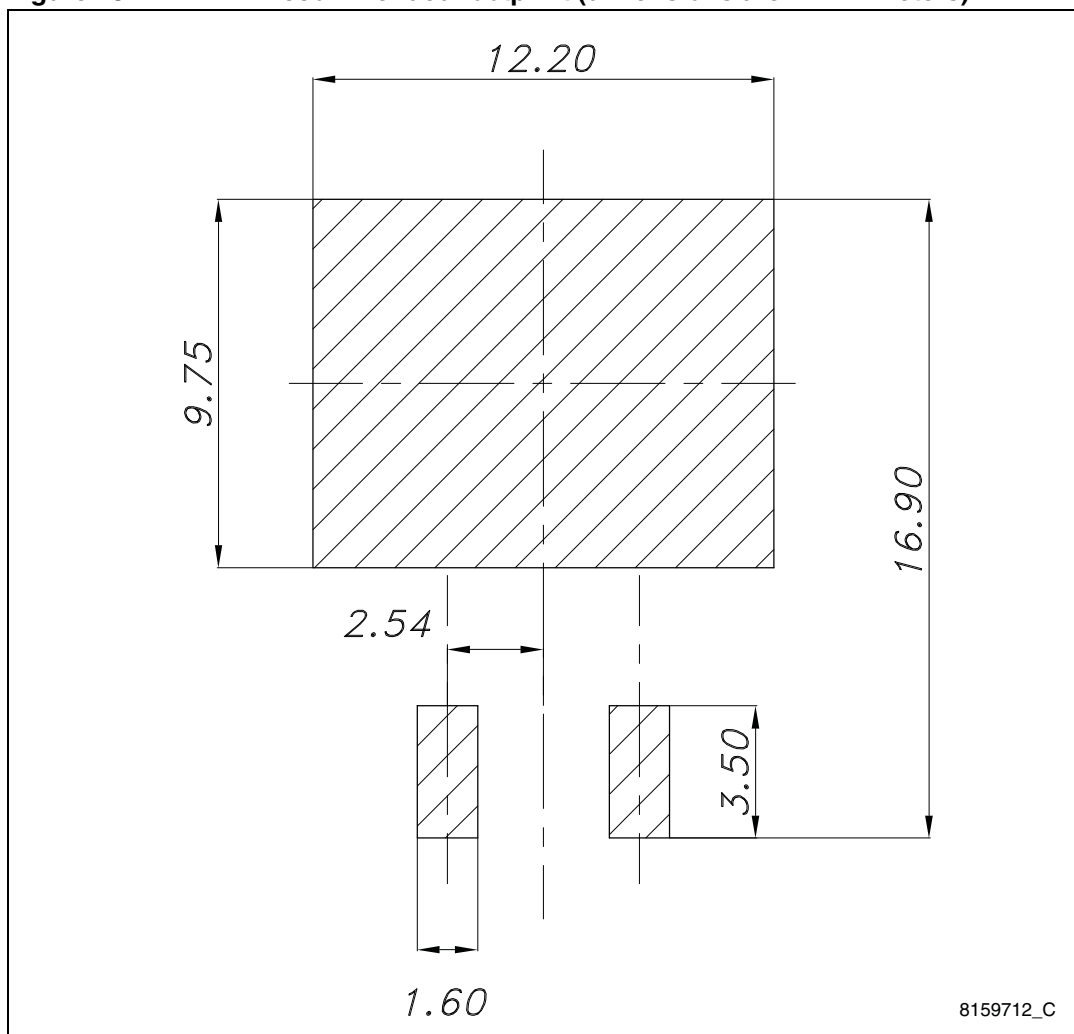
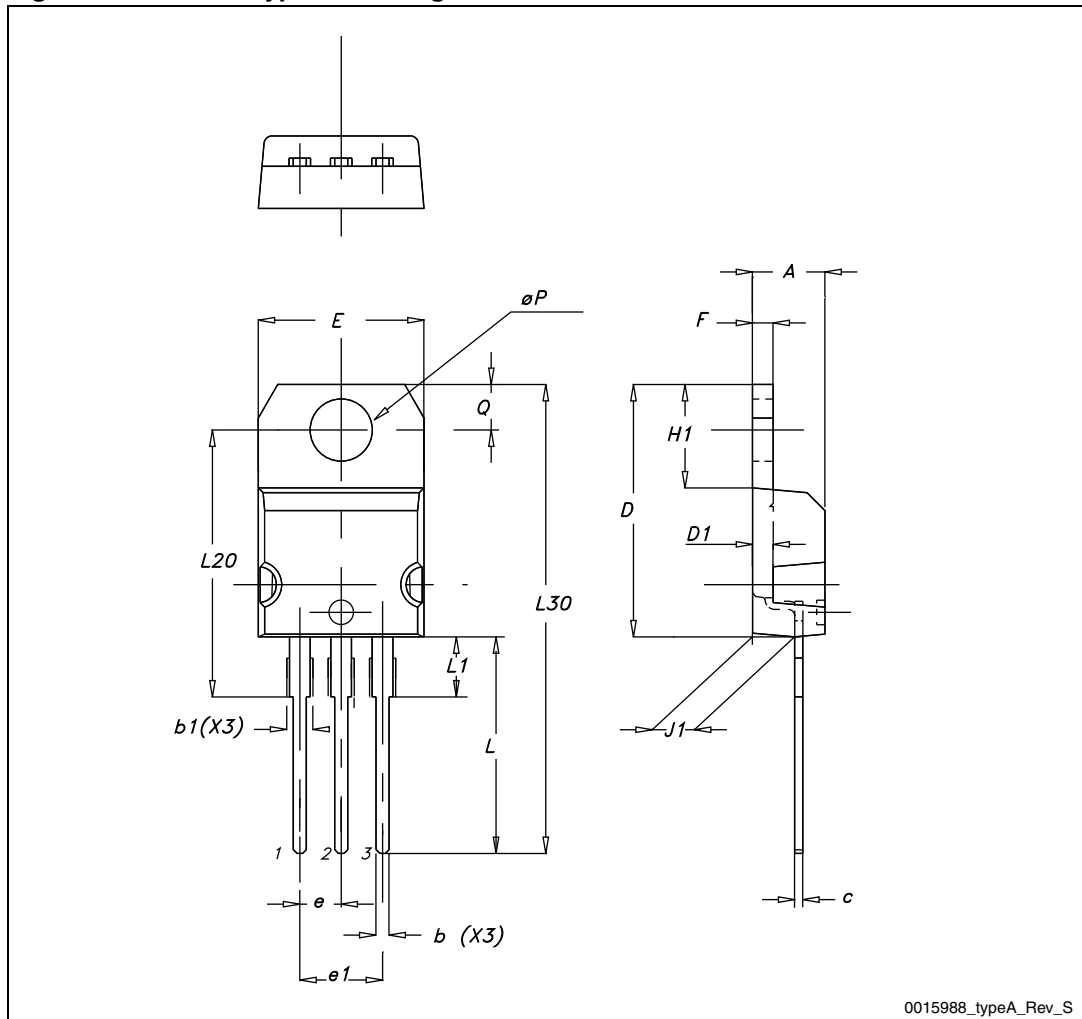
Figure 28. H²PAK-2 recommended footprint (dimensions are in millimeters)

Table 11. TO-220 type A mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	4.40		4.60
b	0.61		0.88
b1	1.14		1.70
c	0.48		0.70
D	15.25		15.75
D1		1.27	
E	10		10.40
e	2.40		2.70
e1	4.95		5.15
F	1.23		1.32
H1	6.20		6.60
J1	2.40		2.72
L	13		14
L1	3.50		3.93
L20		16.40	
L30		28.90	
ØP	3.75		3.85
Q	2.65		2.95

Figure 29. TO-220 type A drawing

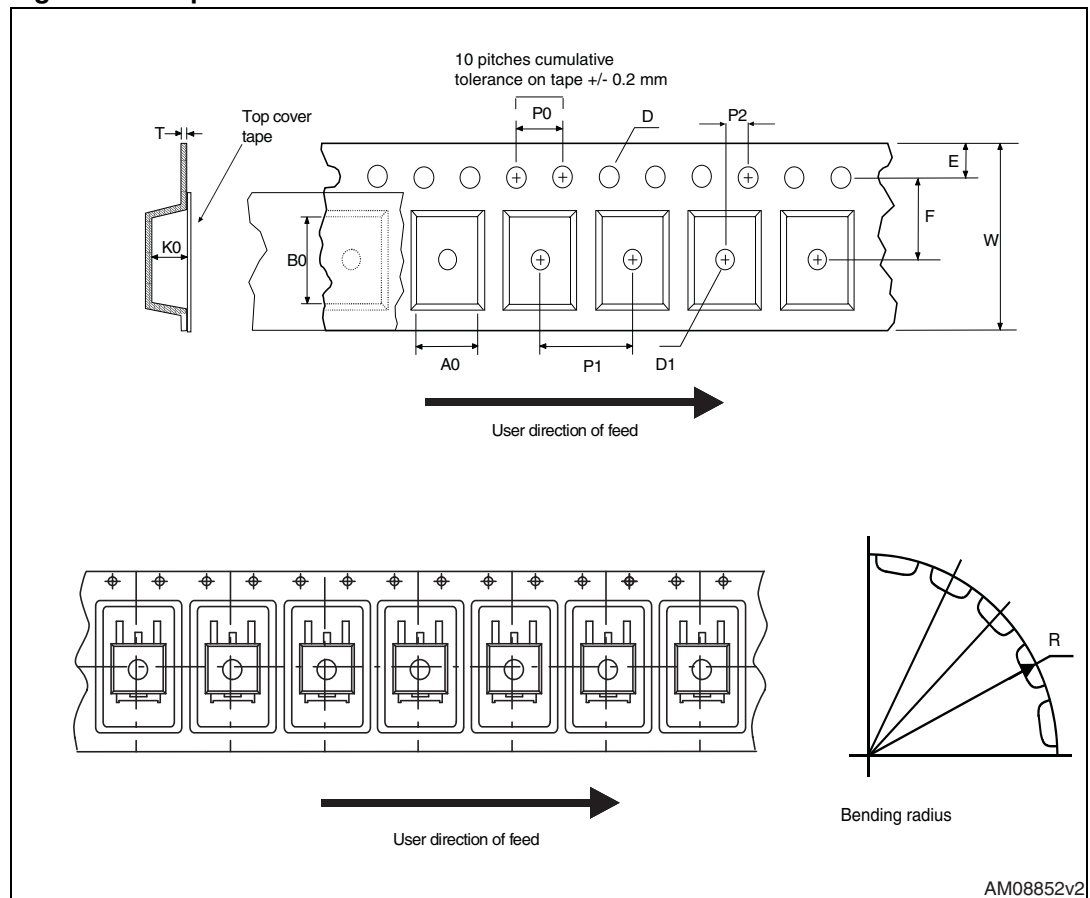


5 Package mechanical data

Table 12. H²PAK-2 tape and reel mechanical data

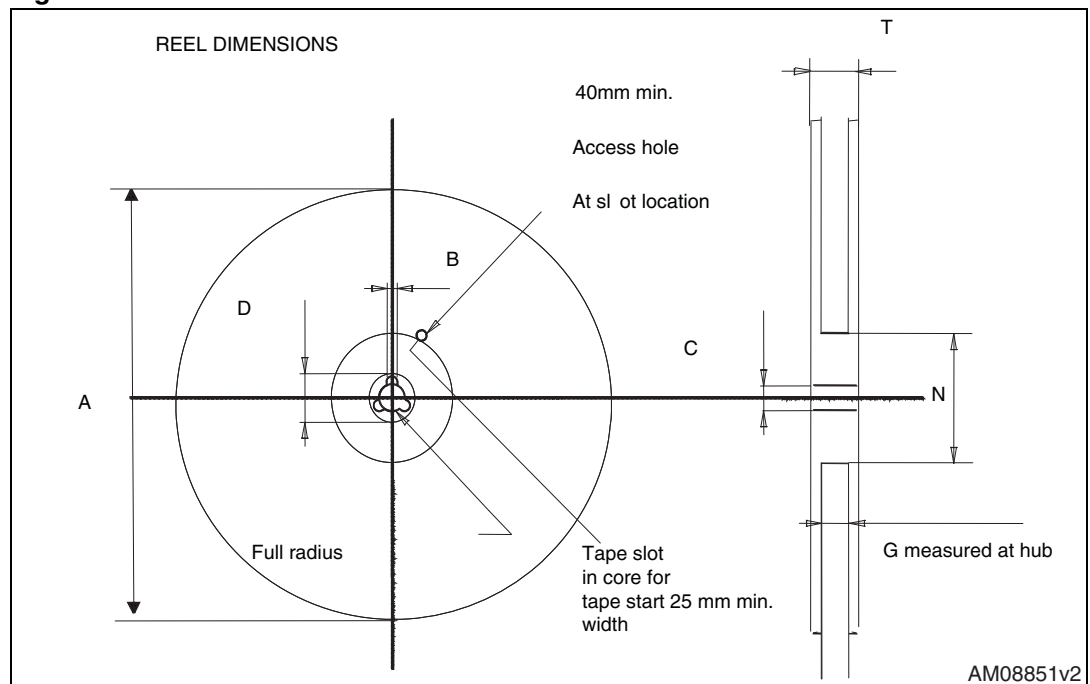
Tape			Reel		
Dim.	mm		Dim.	mm	
	Min.	Max.		Min.	Max.
A0	10.5	10.7	A		330
B0	15.7	15.9	B	1.5	
D	1.5	1.6	C	12.8	13.2
D1	1.59	1.61	D	20.2	
E	1.65	1.85	G	24.4	26.4
F	11.4	11.6	N	100	
K0	4.8	5.0	T		30.4
P0	3.9	4.1			
P1	11.9	12.1	Base qty		1000
P2	1.9	2.1	Bulk qty		1000
R	50				
T	0.25	0.35			
W	23.7	24.3			

Figure 30. Tape



AM08852v2

Figure 31. Reel



AM08851v2

6 Revision history

Table 13. Document revision history

Date	Revision	Changes
24-Feb-2011	1	First version.
07-May-2012	2	Added Section 2.1: Electrical characteristics (curves) . Minor text changes.
07-Nov-2012	3	Added new device in I ² PAKFP and updated the document accordingly. Updated Section 4: Package mechanical data .

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